



Material Content Data Sheet

Sales Product Name	TLE6712G			Issued		28. August 2013		
MA#	MA000064747							
Package	P-DSO-24-8			Weight*		769.20 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	13.713	1.78	1.78	17827	17827
leadframe	inorganic material	phosphorus	7723-14-0	0.057	0.01		74	
	non noble metal	zinc	7440-66-6	0.227	0.03		295	
	non noble metal	iron	7439-89-6	4.540	0.59		5902	
	non noble metal	copper	7440-50-8	184.335	23.96	24.59	239644	245915
wire	noble metal	gold	7440-57-5	2.193	0.29	0.29	2851	2851
encapsulation	plastics	brominated resin	-	5.580	0.73		7255	
	organic material	carbon black	1333-86-4	5.580	0.73		7255	
	inorganic material	antimonytrioxide	1309-64-4	11.719	1.52		15235	
	plastics	epoxy resin	-	60.826	7.91		79077	
	inorganic material	silicondioxide	60676-86-0	474.329	61.65	72.54	616652	725474
leadfinish	non noble metal	lead	7439-92-1	0.360	0.05		467	
	non noble metal	tin	7440-31-5	1.294	0.17	0.22	1682	2149
plating	noble metal	silver	7440-22-4	1.026	0.13	0.13	1333	1333
glue	plastics	epoxy resin	-	0.685	0.09		890	
	noble metal	silver	7440-22-4	2.739	0.36	0.45	3561	4451
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com